



Material Content Data Sheet



Sales Product Name		BSC047N08NS3 G		Issued		19. July 2018		
MA#		MA001247748						
Package		PG-TDSON-8-1		Weight*		122.20 mg		
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	4.414	3.61	3.61	36121	36121
leadframe	non noble metal	iron	7439-89-6	0.038	0.03		309	
	inorganic material	phosphorus	7723-14-0	0.011	0.01		93	
	non noble metal	copper	7440-50-8	37.762	30.89	30.93	309016	309418
wire	non noble metal	copper	7440-50-8	0.065	0.05	0.05	533	533
encapsulation	organic material	carbon black	1333-86-4	0.080	0.07		653	
	plastics	epoxy resin	-	5.661	4.63		46330	
	inorganic material	silicondioxide	60676-86-0	34.128	27.93	32.63	279284	326267
leadfinish	non noble metal	tin	7440-31-5	1.452	1.19	1.19	11879	11879
plating	noble metal	silver	7440-22-4	0.166	0.14	0.14	1355	1355
solder	noble metal	silver	7440-22-4	0.087	0.07		712	
	non noble metal	tin	7440-31-5	0.070	0.06		569	
	non noble metal	lead	7439-92-1	3.322	2.72	2.85	27181	28462
CLIP plating	noble metal	silver	7440-22-4	1.289	1.06	1.06	10552	10552
heatspreader	non noble metal	iron	7439-89-6	0.011	0.01		93	
	inorganic material	phosphorus	7723-14-0	0.003	0.00		28	
	non noble metal	copper	7440-50-8	11.320	9.26	9.27	92635	92756
heat sink CLIP	non noble metal	iron	7439-89-6	0.022	0.02		183	
	inorganic material	phosphorus	7723-14-0	0.007	0.01		55	
	non noble metal	copper	7440-50-8	22.292	18.24	18.27	182419	182657
*deviation	< 10%		Sum in total:			100.00		1000000

Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
2. Infineon Technologies AG and Infineon Technologies AG suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.
3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and contains Pb according RoHS exemption 7a, Lead in high melting temperature type solders.

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